1. (Currently Amended) An apparatus comprising:

a frame;

at least one partial-circle structure above said frame; and

at least one temperature-sensitive release operably connected to said at least one partial-circle structure,

wherein said frame is configured to hold a workpiece having two parts connected by interconnects such that said at least one partial-circle structure is positioned to pass between said two parts and break said interconnects when released by said at least one temperature-sensitive release,

further comprising at least one axle extending vertically through an upper part of said frame and connected to said at least one partial circle structure, wherein said at least one axle is spring-loaded to rotate such that said at least one partial circle structure rotates and passes between said two parts and breaks said interconnects when released by said at least one temperature sensitive release.

2. (Previously Presented) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures operably connected to a plurality of temperature-sensitive releases, and

each of said temperature-sensitive releases are different, such that each of said partial-circle structures is released at a different temperature.

3. (Previously Presented) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures operably connected to a plurality of temperature-sensitive releases, and

wherein rotational paths of said partial-circle structures partially overlap.

4. (Previously Presented) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures operably connected to a plurality of temperature-sensitive releases, and

wherein said workpiece is positioned between said partial-circle structures.

5. (Previously Presented) The apparatus in claim 1, wherein said at least one partial-circle structurecomprises less than a three-quarter portion of a disc that is approximately .01 inches thick.

6. (Cancelled).

7. (Original) The apparatus in claim 1, wherein said temperature-sensitive release is adapted to release said partial-circle structure at a temperature above a melting point of said interconnects.

8-20. (Cancelled).

21. (Previously Presented) The apparatus of claim 1, wherein said two parts comprise one of a chip and substrate and a substrate and carrier and wherein said frame further comprises at least one reservoir positioned to receive material from said interconnects broken by said at least one partial-circle structure.

22-27. (Cancelled).